

L Number	Hits	Search Text	DB	Time stamp
-	227	438/658.ccls.	USPAT	2003/11/18 10:36
-	137	438/658.ccls. and conductive	USPAT	2003/11/18 10:36
-	136	438/658.ccls. and conductive and layer	USPAT	2003/11/18 10:37
-	68	438/658.ccls. and conductive and layer and via	USPAT	2003/11/18 10:37
-	31	438/658.ccls. and conductive and layer and via and electromigration	USPAT	2003/11/18 10:37
-	5	438/658.ccls. and conductive and layer and via and electromigration and dopant	USPAT	2003/11/18 10:37
-	1	438/658.ccls. and conductive and layer and via and electromigration and dopant and aluminum and concentrat\$4 and atomic	USPAT	2003/11/18 10:38
-	2	438/658.ccls. and conductive and layer and via and electromigration and dopant and aluminum and concentrat\$4	USPAT	2003/11/18 12:27
-	5	438/658.ccls. and conductive and layer and via and electromigration and dopant and aluminum	USPAT	2003/11/24 11:49
-	51	438/658.ccls. and "conductive layer"	USPAT	2003/11/21 14:11
-	50	438/658.ccls. and "conductive layer" and substrate	USPAT	2003/11/21 14:11
-	21	438/658.ccls. and "conductive layer" and substrate and "dielectric layer"	USPAT	2003/11/21 14:11
-	15	438/658.ccls. and "conductive layer" and substrate and "dielectric layer" and "barrier layer"	USPAT	2003/11/21 14:11
-	12	438/658.ccls. and "conductive layer" and substrate and "dielectric layer" and "barrier layer" and via	USPAT	2003/11/21 14:12
-	0	438/658.ccls. and "conductive layer" and substrate and "dielectric layer" and "barrier layer" and via and dopant	USPAT	2003/11/21 14:12
-	6	438/658.ccls. and "conductive layer" and substrate and "dielectric layer" and "barrier layer" and via and dop\$4	USPAT	2003/11/21 14:14
-	6	438/658.ccls. and "conductive layer" and substrate and "dielectric layer" and "barrier layer" and via and dop\$4 and electromigration	USPAT	2003/11/21 14:15
-	2	438/658.ccls. and "conductive layer" and substrate and "dielectric layer" and "barrier layer" and via and dop\$4 and electromigration and atomic	USPAT	2003/11/21 15:19
-	0	438/658.ccls. and "conductive layer" and substrate and "dielectric layer" and "barrier layer" and via and dop\$4 and electromigration and atomic and implant	USPAT	2003/11/21 15:19
-	2	438/658.ccls. and conductive and layer and via and electromigration and dopant and aluminum and ion	USPAT	2003/11/24 11:49
-	2	438/658.ccls. and conductive and layer and via and electromigration and dopant and aluminum and ion and gas	USPAT	2003/11/24 11:50